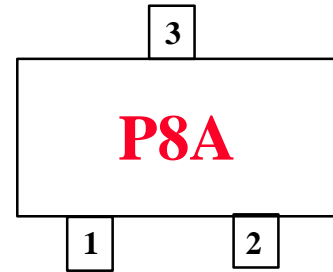


# FLLD261

## HIGH CONDUCTANCE LOW LEAKAGE DIODE

**Pd** ... .350 mW @ **T<sub>A</sub>** = 25 Deg C  
**Bv** ... .200 V (MIN) @ **I<sub>R</sub>** = 5 uA

**PACKAGE**  
TO-236AB (Low)



### ABSOLUTE MAXIMUM RATINGS (NOTE 1)

#### TEMPERATURES

Storage Temperature -55 to +150 Degrees C  
Operating Junction Temperature -55 to +150 Degrees C

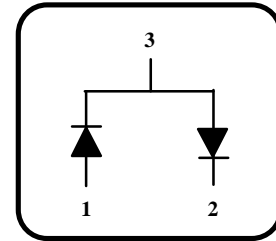
### POWER DISSIPATION (NOTES 2 & 3)

Total Device Dissipation at **T<sub>A</sub>** = 25 Deg C 350 mW  
Derating Factor per Degree C 2.8 mW

### VOLTAGES & CURRENTS

WIV	Working Inverse Voltage	100 V
I <sub>O</sub>	Average Rectified Current	250 mA
I <sub>F</sub>	DC Forward Current	600 mA
i <sub>f</sub>	Recurrent Peak Forward Current	700 mA
i <sub>f</sub> (surge)	Peak Forward Surge Current	
	Pulse width = 1 second	1.0 A
	Pulse width = 1 microsec	3.0 A

### CONNECTION DIAGRAMS

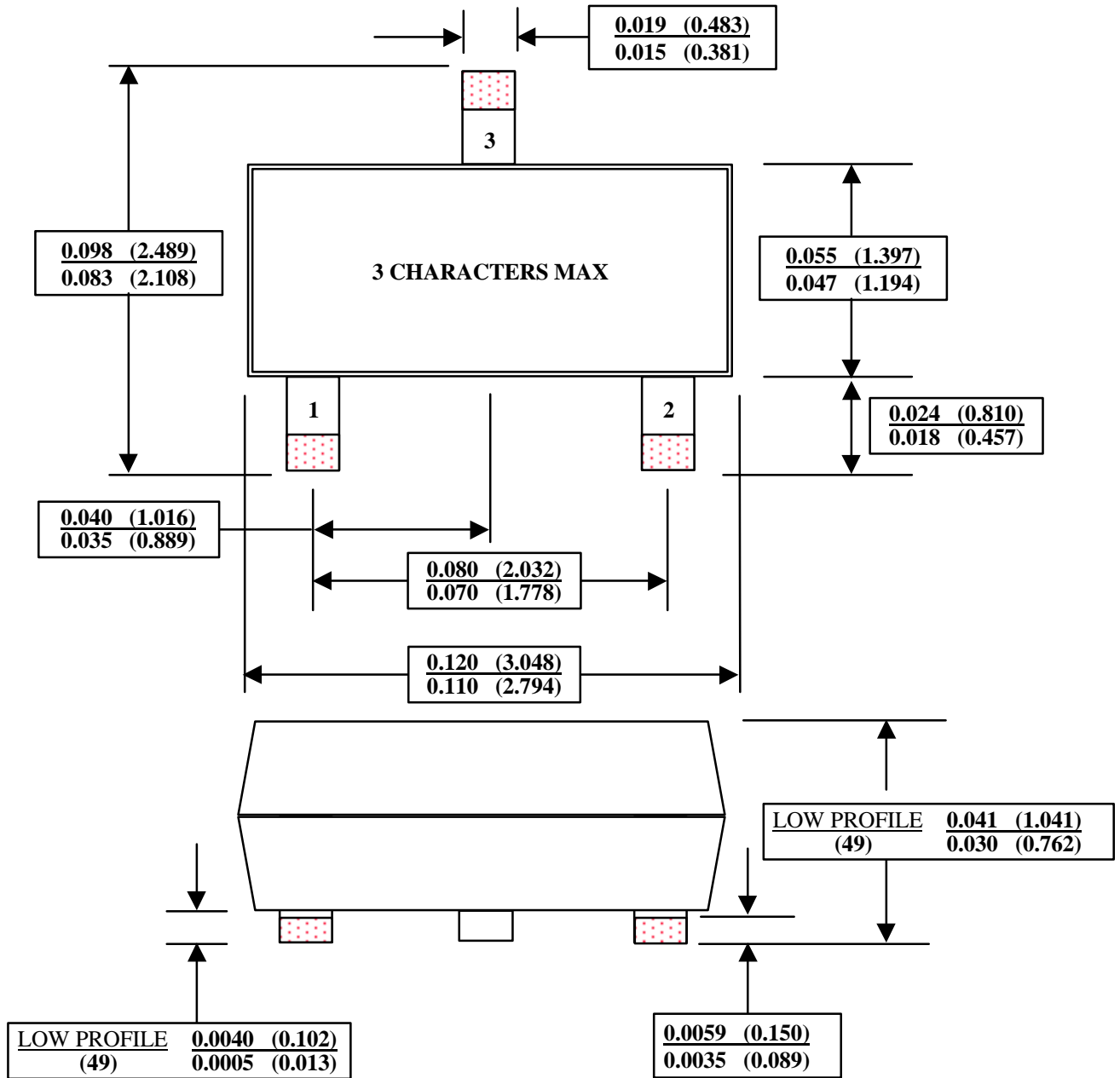


### ELECTRICAL CHARACTERISTICS (25 Degrees C Ambient Temperature unless otherwise stated)

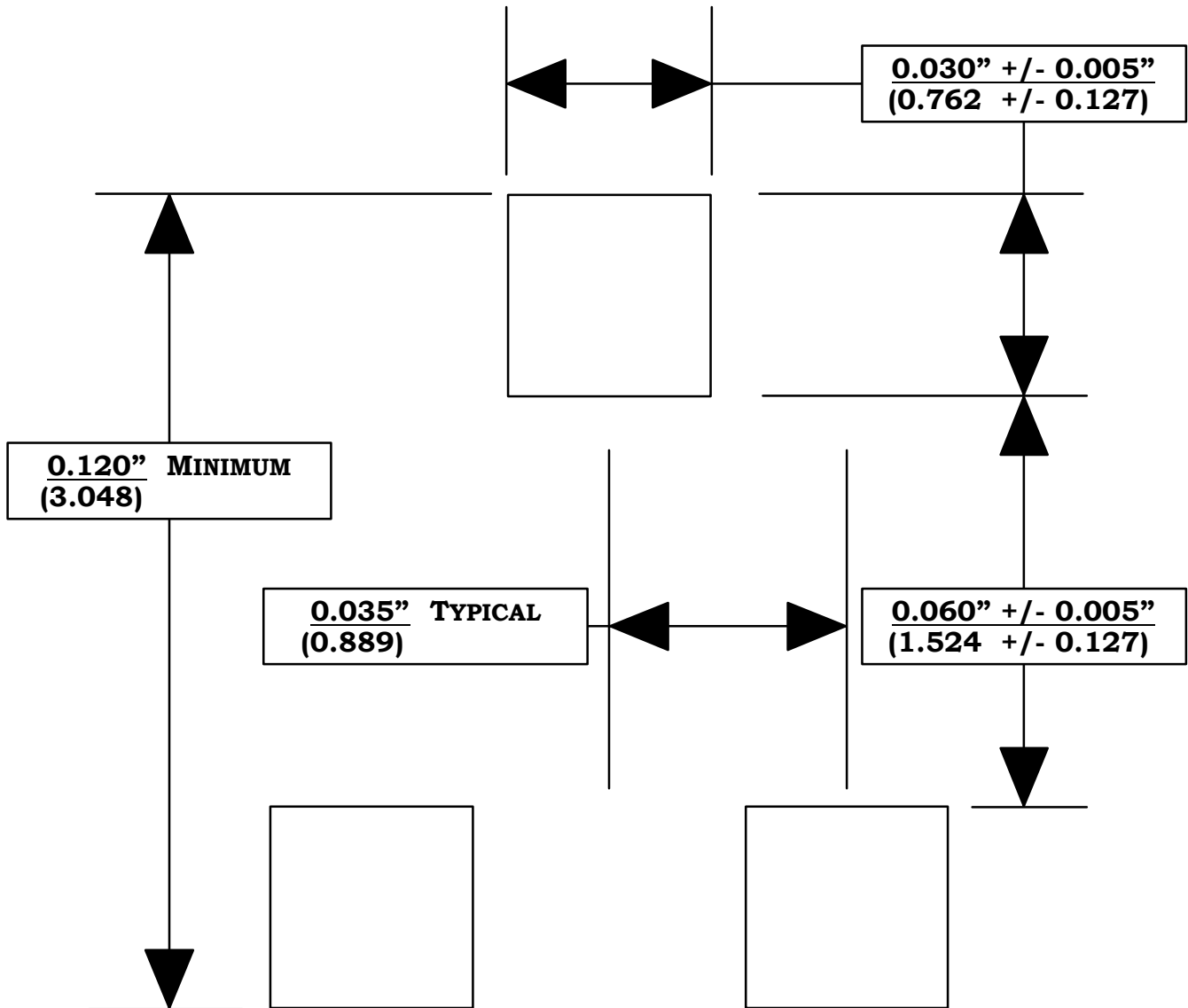
SYM	CHARACTERISTICS	MIN	MAX	UNITS	TEST CONDITIONS
B <sub>v</sub>	Breakdown Voltage	200		V	I <sub>R</sub> = 5.0 uA
I <sub>R</sub>	Reverse Voltage Leakage Current		5.0 5.0	nA uA	V <sub>R</sub> = 100 V V <sub>R</sub> = 100 V    T <sub>A</sub> = 150 Deg C
V <sub>F</sub>	Forward Voltage		1.40	V	I <sub>F</sub> = 200 mA
C <sub>T</sub>	Diode Capacitance		4.0	pF	V <sub>R</sub> = 1.0 V    f = 1.0 MHz
T <sub>RR</sub>	Reverse Recovery Time		400	ns	I <sub>F</sub> = I <sub>R</sub> = 50 to 400 mA I <sub>RR</sub> = 10% I <sub>R</sub> R <sub>L</sub> = 100 ohms
T <sub>FR</sub>	Forward Recovery Time		10	ns	I <sub>F</sub> = 10 mA
V <sub>FM</sub>	Peak Forward Voltage		0.9 Typ	V	I <sub>F</sub> = 10 mA Rise Time = 5 ns +/-20%

#### NOTES:

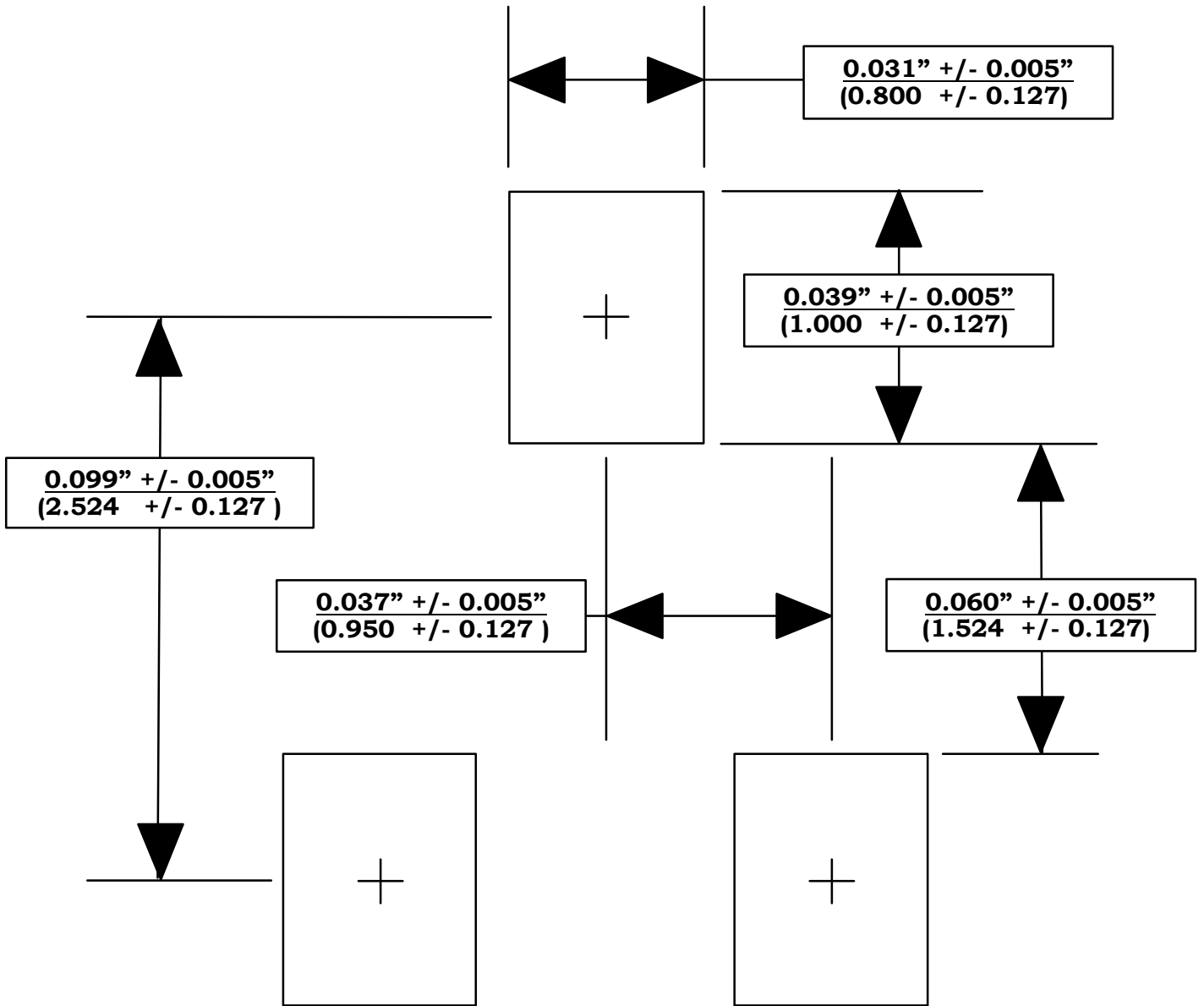
1. These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.
2. These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.



**SOT-23 (DIODE)**  
TO-236AB (LOW PROFILE)  
11-March-1997



**RECOMMENDED SOLDER PADS  
FOR  
SOT-23**



**RECOMMENDED SOLDER PADS  
FOR  
U.S., European & Japanese (SC-59)  
SOT-23**

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